

COPOLYMERIZED POLYIMIDE, COPOLYMERIZED POLYIMIDE RESIN MOLDING AND THEIR PRODUCTION

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Inventor(s): SAWAZAKI KOICHI; KUBO MICHIHIRO; MATSUDA TOSHIKAZU

Applicant(s): DU PONT TORAY CO LTD

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Abstract

PROBLEM TO BE SOLVED: To obtain a polyimide copolymer which can produce a molded product of high elastic modulus, low thermal expansion and low water absorption and is useful as a TAB base film by molecularly binding a specific block polyimide component to a randomly copolymerized polyimide component.

SOLUTION: (A) A polyimide block component from an aromatic diamine of a rigid structure of formula I (X is H, a halogen, carboxyl, a lower alkyl, a lower alkoxy) such as p-phenylenediamine (A1) and an aromatic tetracarboxylic acid, for example, pyromellitic acid, 3,3',4,4'- biphenyltetracarboxylic acid or 3, 3',4,4'-benzophenone-tetracarboxylic acid (A2) and (B) a polyimide random copolymer component from an aromatic diamine of a flexible structure of formula II (Y is X; A is O, S, CO, SO, SO₂, CH₂), for example, 4,4'-diaminodiphenyl ether (B1) and 2 or more kinds of A2 are molecularly bonded to each other.

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